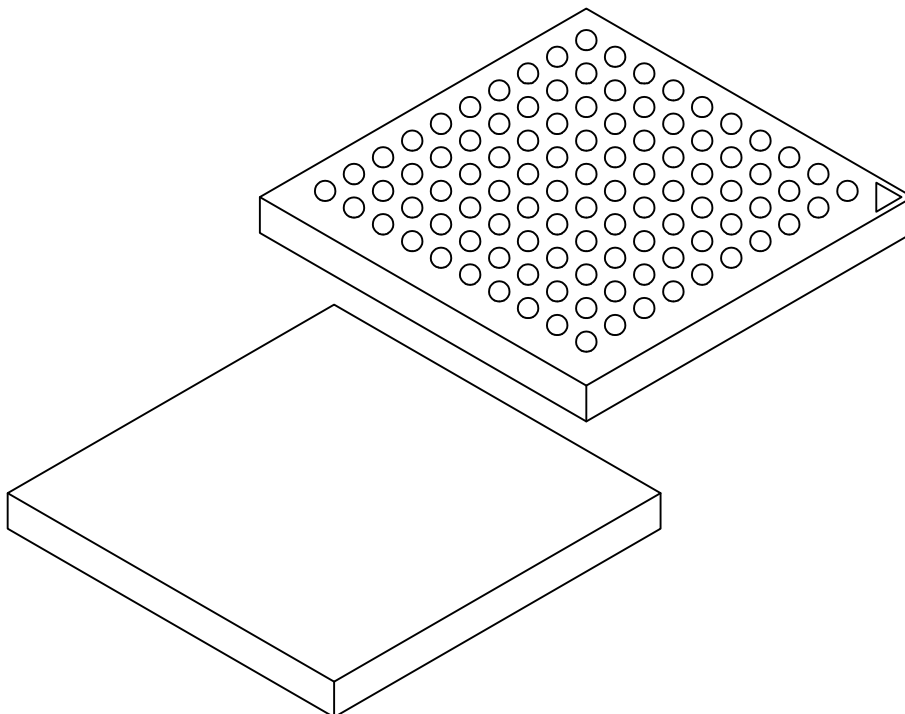


100-Ball Plastic Thin, Fine Pitch Ball Grid Array Package (HJB) - 9x9 mm Body [TFBGA] Atmel Legacy Global Package Code CPR

Note: For the most current package drawings, please see the Microchip Packaging Specification located at <http://www.microchip.com/packaging>



Dimension Limits	Units	MILLIMETERS		
		MIN	NOM	MAX
Number of Terminals	N	100		
Pitch	e	0.80 BSC		
Overall Height	A	-	-	1.20
Ball Height	A1	0.25	-	0.40
Molded Package Height	A2	0.65	-	-
Overall Length	D	9.00 BSC		
Overall Pitch	D1	7.20 BSC		
Overall Width	E	9.00 BSC		
Overall Pitch	E1	7.20 BSC		
Terminal Diameter	b	0.35	-	0.50

Notes:

1. Terminal A1 visual index feature may vary, but must be located within the hatched area.
2. Dimensioning and tolerancing per ASME Y14.5M
BSC: Basic Dimension. Theoretically exact value shown without tolerances.
REF: Reference Dimension, usually without tolerance, for information purposes only.
3. Supersedes C04-21111 and C04-21503